

THE RF PROTECTION INTERLOCK SYSTEM

PROTOTYPE VERIFICATION*

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Abstract

The Radio Frequency Protection Interlock system plays a vital role in the LLRF-related/dependent accelerator sections Protection. Its main role is to collect information from a number of different sensors and indicators around the nearest cavities and cryomodules and provide instant RF signal termination in case of safety threshold violation. This submission describes a newly designed RFPI system tailored to the requirements of Proton Improvement Plan II (PIP-II). The proof of concept prototype of this system has been built. The paper includes also the PIP2IT (PIP-II integrated test stand) environment evaluation test results and findings as input to the next full-scope prototype design.

INTRODUCTION

The Low Level RF (LLRF) control systems are widely used in normal and superconducting accelerators to provide optimal conditions for energy transfer from accelerating structures to the accelerated proton or electron beam. The performance of this system can determine overall beam parameters hence influence conditions of laser light or neutron beam generation or others - depending on the given infrastructure type.

The LLRF system has to ensure instantaneous correction of the amplitude and phase parameters of electromagnetic accelerating waves. In the case of superconducting resonators working as standing wave systems its main focus is the execution of the fast feedback algorithms responsible for such actions. To perform its role efficiently LLRF system has to be provided with strictly defined operating conditions for the whole accelerating structure. A system that is responsible for such conditions monitoring and system hardware protection exists in many accelerator implementations. In the case of the newly designed Proton Improvement Plan II (PIP-II) H- accelerator in Fermilab [1], such system has been named Radio Frequency Protection Interlock (RFPI).

The RFPI system's main role is to monitor various cryomodule components' status values and drop the permit signals in case any predefined safety thresholds are exceeded [2]. To gather comprehensive knowledge about subsystems' current state the RFPI has to observe several various signals from vacuum, cryogenics, temperature sensors, RF signals

leak sensors, electron pick-up, input fundamental coupler high voltage power supply, solid state amplifier status, LLRF system status and others.

For many years the RFPI system developed and implemented earlier in Fermilab provided constant protection for systems operated in various locations of local accelerator infrastructure. Together with the new design of the LLRF system, it has been also decided that the PIP-II dedicated RFPI system needs to be adapted to the specific project needs. The requirement concerning system redesign according to modern electronic standards was not the only one. A newly designed RFPI system needs to be modular and provide configurable sub-sets of input signals depending on the deployment place. Because of that not only the flexibility in system hardware configuration has to be delivered. The protection function logic needs to be also susceptible to reconfiguration and scaling. What is more, a single PIP-II RFPI system has to protect from one to four LLRF systems (and resonators) gathered in a single (or different) cryomodule.

The proposed new design fulfills the requirements concerning modularity, scalability, and reconfiguration challenges. The new solution incorporates dedicated, custom-designed signal-conditioning modules connected to the carrier board via custom FMC modules. This component contains an FPGA chip that holds and executes protection function logic. Hence configuration can be modified by removing or introducing a given conditioning submodule and adjusting the protection function when needed. This approach foreseen also the System On-Chip (SOC) chip configuration usage for better integration of the EPICS control system dedicated IOC with the RFPI infrastructure.

The first version of the system has been designed and produced in the form of a Proof of Concept (PoC) prototype [3]. This version of the system consists of custom-designed signal conditioning and dedicated interface FMC modules as well as COTS components integrated into a single RFPI instance. Although the PoC does not possess enough input channels to cover the full four cavity set-up its main goal was the verification of each input channel type conditioning/processing quality and performance.

PROOF OF CONCEPT PROTOTYPE HARDWARE STRUCTURE

The RFPI system PoC hardware structure is illustrated in Fig. 1.

The PoC system consists of the following modules:

Hardware

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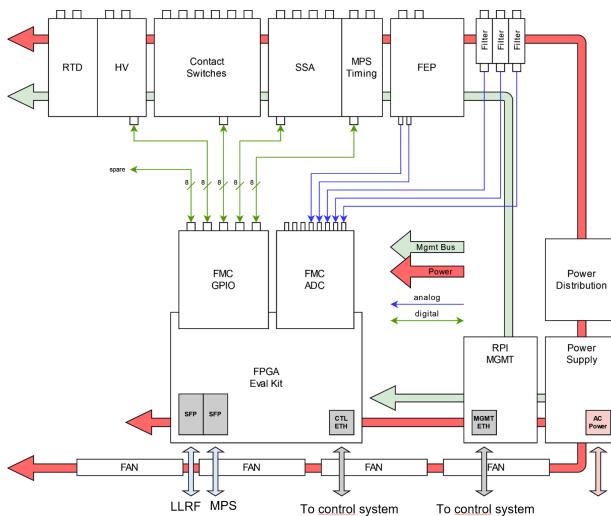


Figure 1: The block diagram of the PoC structure.

- Main logic realization unit
- FPGA Mezzanine Card (FMC) interface modules
 - FMC General Purpose IO (GPIO) board
 - FMC ADC board
- Input/output signals conditioning modules
 - Contact Switches board
 - Field emission probe (FEP) module
 - RTD and coupler bias voltage board
 - Non-ionising Radiation Probe module
 - Solid State Amplifier (SSA) and LLRF inhibit submodule
- Management and Diagnostics

Main Logic Unit

The ZCU106 (by Xilinx) development board was the main carrier of the PoC design. This module contains Zynq UltraScale+™ FPGA chip and a quad-core Arm Cortex A53 application processor as well as two FMC slots. The FPGA has enough resources to execute full protection function logic for the RFPI system. The Arm processor delivers the required resources for the EPICS IOC that manages and monitors main logic functionality. The available FMC slots have been used to interface in/out signals conditioning modules via dedicated analog and digital FMC boards.

FMC Modules

To exchange signals between the main FPGA and conditioning boards two FMC modules have been designed and produced. The FMC GPIO module provides 40 GPIO (8 for each board) and 2 power connections. To effectively work with conditioning boards each GPIO can cope with signals up to 50 MHz (see Fig. 2).

In addition, the FMC ADC module has been developed (see Fig. 3). It provides 8 ADC channels (14-bits, 25 MS/s) to interface FEP and NIRP conditioning modules. As NIRP requires RF signals detection the FMC ADC has been

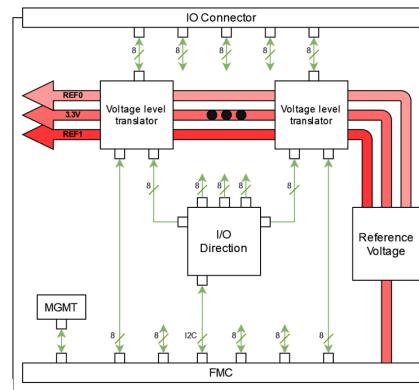


Figure 2: The FMC GPIO module block diagram.

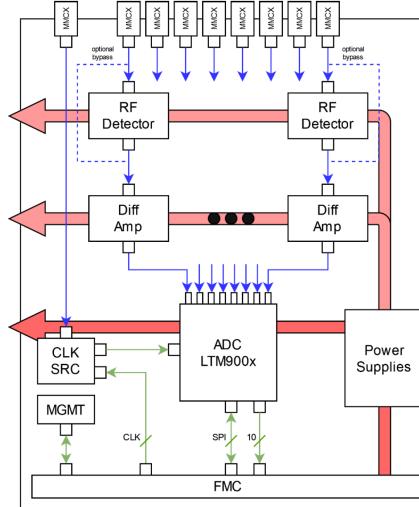


Figure 3: The FMC ADC module block diagram.

equipped optionally with RF detectors. Each channel of this board can be configured to use or bypass the RF detector stage.

Input and Output Signals Conditioning Modules

To cover the RFPI input and output interface requirements five different signal conditioning (SC) modules have been proposed, designed, and produced in-house. There were eight different groups of signals identified for the RFPI setup. That is why single SC congregate one or more signal type. As the PoC main goal was each type of channel implementation verification the SC modules contain a limited quantity of channels that fulfill requirements for single cavity and cryomodule RFPI protection.

The Contact Switches SC The RFPI-critical signals in the form of open/close PLC-based switches were gathered on the Contact Switch module (see Fig. 4). This device generates different voltages depending on the monitored signal type. The design of this part allows for different HW type settings (NC or NO) and provides cable diagnostics capabilities as well as signal latching on each input and masking

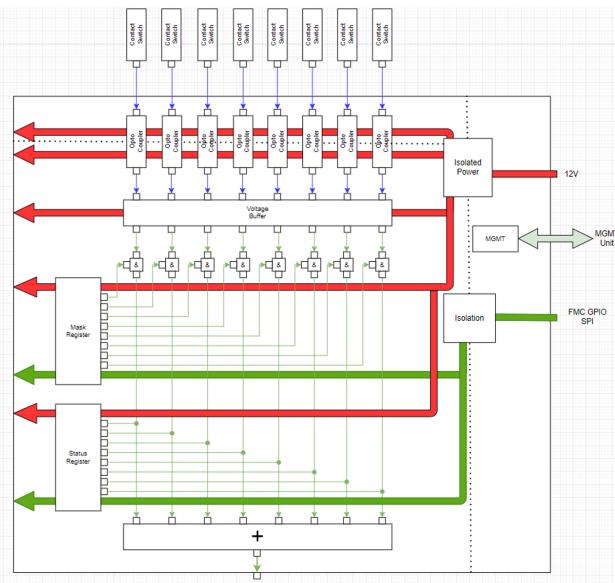


Figure 4: The contact switches signal conditioning module block diagram.

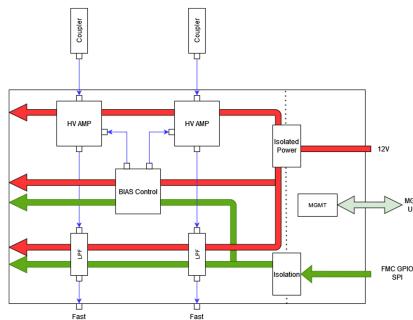


Figure 5: The FEP SC diagram.

functionalities. The helium pressure and level, window cooling airflow permit, coupler vacuum permit, beam vacuum permit are examples of signals monitored by this module.

The Field Emission Probe (FEP) SC The electron pick-up channel monitoring is covered by the field emission probe conditioning module (see Fig. 5). To detect micro- and nano-ampere level current dedicated highly sensitive circuit has been adapted from previous RFPII realization. To increase and improve the detection level the biasing voltage was provided too.

The Resistance Temperature Detector (RTD) and Coupler Bias High Voltage Power Supply SC The PT-103 unit-based temperature read-outs from two different locations next to the cavity need to be monitored. According to the requirements, the four-wire measurement configuration has been provided. Other channels on this module (spare analog) were dedicated for coupler bias HV power supply current and voltage diagnostics as depicted in Fig. 6.

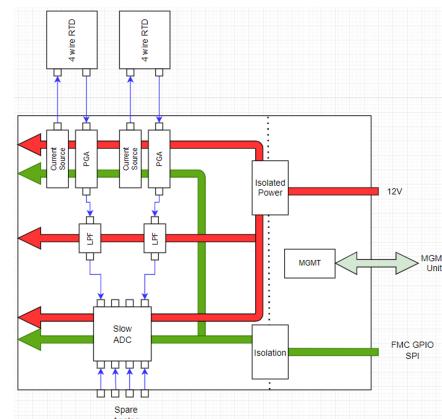


Figure 6: The RTD/HV PS SC diagram.

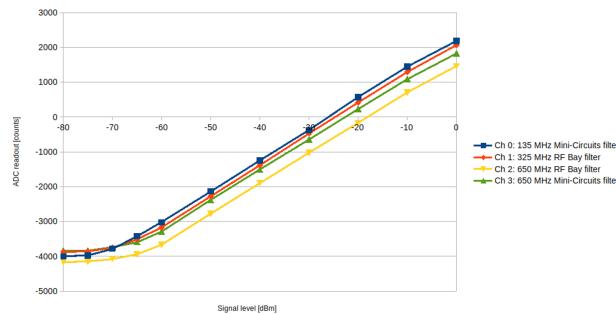


Figure 7: The RF detector characterization for different passband filters used in the design.

The Non-Ionising Radiation Probe The RF leakage detection was covered separately, outside of the design SC modules. Three different RF passband filters were examined for PIP-II typical frequencies (162.5, 325, 650 MHz) (see Fig. 7). In case of the PoC an extensive leakage was reported thanks to the mentioned filter and RF detector placed at the input of chosen FMC-ADC channels. The digitized version of the NIRP signal was delivered later to the main logic unit and included in the protection function estimation.

The Solid State Amplifier (SSA) Permit SC The RFPI system communicates certain system failures via four output signals. Some or all of these permits are dropped in case of system fault detection. Then the RFPI system drops the 5 V signal and disables LLRF output or Solid State Amplifier output or its DC voltage and finally also it sends information to the Machine Protection System (MPS).

Management and Diagnostics

The prototype sections' working conditions are supervised by the dedicated Management and Diagnostics sub-circuit. Its main role is to gather information from voltage, current and temperature sensors from individual SC modules and other locations. Moreover, via relay array, it is capable of switching on/off power to a given part of the RFPI. Thanks to that it protects the SC modules (and main unit) from

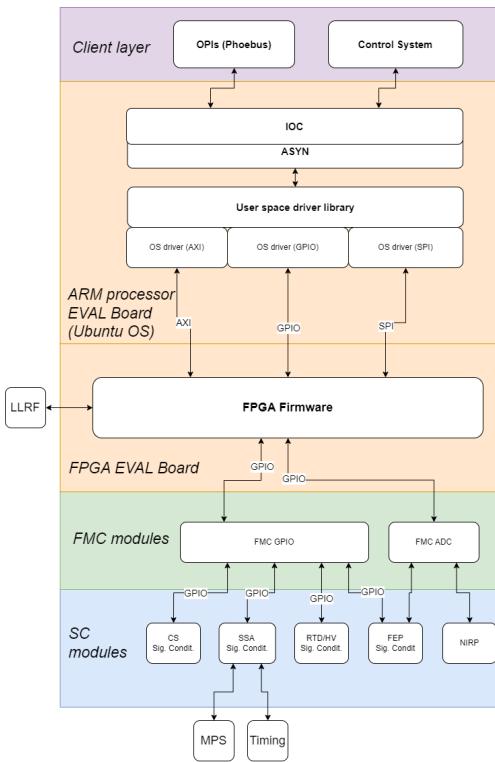


Figure 8: The main logic unit software diagram.

long-term over-voltage or over-current issues. As management and diagnostics is also responsible for fans control it is regulating airflow in the chassis in case of overheating.

Finally, this part of the system implements also the main logic unit watchdog functionality which is crucial for the whole RFPI system disabling while the main logic unit response is not reliable.

SOFTWARE STRUCTURE

The main logic unit software structure is presented in Fig. 8. The lowest layer is the FPGA firmware part. On this level, the pre-processed digital input signals are gathered and the main protection function logic is executed. The output signals state is determined on this level too. The firmware interfaces to the higher operating system (OS) level via AXI, GPIO, SPI channels. The ARM processor (located on the same SoC) uses Ubuntu distribution OS drivers to establish communication through these channels. The user space library not only provides access to the FW registers. It provides already the functionality needed for the RFPI configuration (like acceptable signal thresholds set/get or individual input channels masking on the protection function level).

The upper SW layer EPICS IOC ASYN module actively uses the user space library to communicate with the hardware. The top layer here is the OPI part that provides GUI functionalities and access for the system operator and experts.

Hardware

Hardware Technology

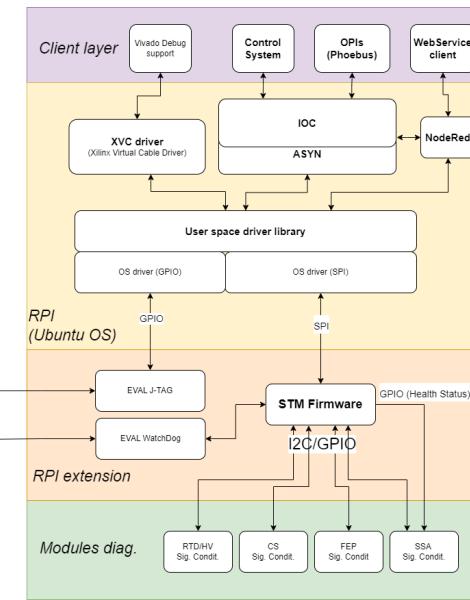


Figure 9: The management and diagnostics SW diagram.

Different software layers have been identified and implemented for the management and diagnostics sub-system. The lowest layer is the firmware of the STM32 microcontroller. As depicted in Fig. 9 this part is responsible (among the others) for diagnostics sensors readouts, health status signal preparation as well as watchdog signal for main logic unit FPGA.

The next layer is already the operating system part. As in the case of the main unit Ubuntu 22.04 distribution was used. The OS drivers provide sufficient functionality to interface between STM32 firmware and the user space driver library. On top of that we have developed the dedicated EPICS IOC together with supporting OPI's. The XVC (Xilinx Virtual Cable) driver is a part of this software and provides a debugging and programming interface for the main unit FPGA.

PROTOTYPE EVALUATION

PoC Evaluation on the Test Bench

Evaluation of each channel type happened during the signal conditioning modules post-production testing. The hardware designers provided also dedicated sub-circuits to provide the required input signals parameters. These setups allowed the determination of the particular channel performance and limits. Then the complete prototype was built from all the described earlier components. We have prepared the PoC in the form of 3U, 19-inch box with most input/output interfaces at the back-panel (see Fig. 10). For simplicity either BNC or RJ45 connectors were used for most signals.

Post-integration testing included individual channels evaluation together with protection function logic implementation checks. The verification on the electrical level was possible thanks to developed software modules. They provide configuration and management capabilities to the expert



Figure 10: The RFPI PoC box picture (ref. to IPAC paper).

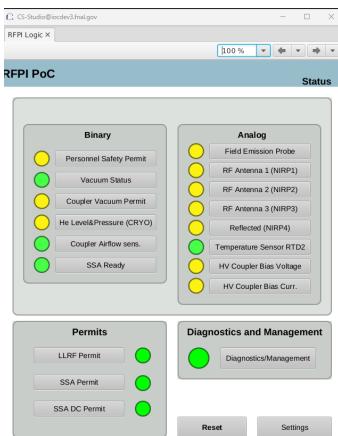


Figure 11: The PoC main logic unit operation OPI window.

during test runs. Performed tests proved parameters expected from the system modules. Some room for improvement was recognized especially for the FEP SC module. It needs to be emphasized that the work on the LLRF and other subsystems design (within PIP-II) is still ongoing. This influence also requirements list for the RFPI systems.

Prototype Evaluation at Cryomodule Test Facility (Fermilab)

The final evaluation of the PoC device took place at the PIP-II integrated test stand in Fermilab. Due to the limited quantity of the prototype inputs it has been agreed that the PoC test will include single cavity protection. After initial installation, each RFPI input was verified by an artificial test signal induced by real subsections of the cryomodule systems. An example of the individual channel testing procedure step is presented in Fig. 11. The active signals that participate in the protection signal generation are indicated by green LEDs, and other masked signals - by yellow LED.

Examples of the PoC system performance for induced signals are presented in Figs. 12 and 13.

Achieved protection system response, when LLRF permits have been dropped by RFPI were 9 μ s and 2 μ s for “cryo permit” and NIRP signals respectively. These results are positive and much better than the allowed system reaction time. The FPGA based system not only provided protection function response within given limits but also delivered post-mortem information about signals chronology.

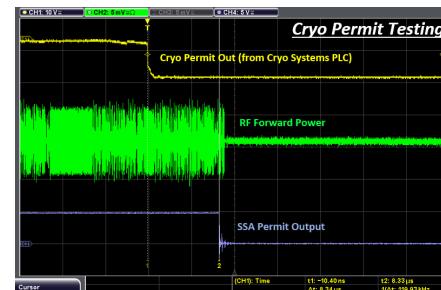


Figure 12: The forward RF power blocking after cryo permit signal activation.

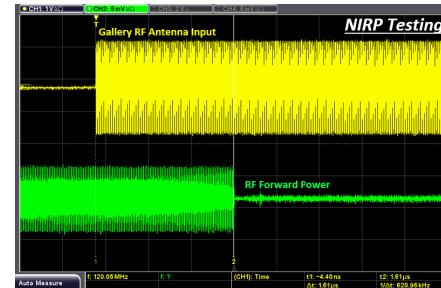


Figure 13: The forward RF power blocking after NIRP signal introduction.

The final test of the PoC included single high beta (HB650) cavity protection during several hours of operation in different conditions. Also in this case the test result was positive. The PoC behaved as expected and did not introduce any false protection action.

CONCLUSION

The PIP-II accelerator is in the construction phase. Since it is a good opportunity to push some linac systems to the new technologies. An example can be the FPGA-based protection RFPI system. The initial prototype design and produced by the FNAL-DMCS/LUT effective collaboration fulfills the majority of the requirements defined for such a system. Although not equipped with the final channel quantity, the PoC proved its reliability and performance in test-bench and real accelerator environment studies. Technical conclusions drawn from this device are already part of the ongoing full-scale prototype design.

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